

# 10<sup>th</sup> International Congress on Thermal Stresses 2013

May 31-June 4, 2013, Nanjing, China  
First Announcement and Call for Papers



## TIME AND PLACE

The Congress will be held from May 31 to June 4, 2013, on the campus of the Nanjing University of Aeronautics and Astronautics, Nanjing, China. The accommodation will be organized in nearby hotels within walking distance.

## AIM

The objectives of the Congress are to provide a forum for scientists and engineers from academia, research laboratories, and industry from all over the world who are involved in the field of thermal stresses to exchange ideas and to extend further cooperation among participants. The Congress should forge cooperative links between researchers and engineers by bringing them to one place where they present their achievements and conduct discussions.

## TOPICS

This is a conference on theoretical and applied mechanics of solids, with particular focus on the following, but not limited to them:

- Thermal Stresses and Deformations
- Thermoelasticity and Viscoelasticity
- Thermal Stresses in
  - Contact Mechanics,
  - Dynamic Problems,
  - Fracture and Fatigue of Heterogeneous Materials and Manufacturing
- Thermo-Hygro-Mechanics
- Thermo-Biomechanics
- Thermal Shock
- Continuum Thermomechanics
- Heat Conduction, Convection and Radiation Problems
- Experimental Methods in Thermomechanics
- Computational Methods in Thermomechanics
- Control of Thermal Structures

- Instability and Localization under Thermomechanic Loading
- Inverse and Optimization Methods in Thermomechanics
- Thermal Stresses in Smart Materials
- Thermal-Induced Fracture of Smart Materials

## ABSTRACTS, POSTERS AND PAPERS

An abstract of presentation of about 500 words or of half-page length with title, name, address, phone/fax number and e-mail address should be submitted to the Secretariat of TS 2013. Decision on the presentation form (oral or poster) will be sent to the authors. And detailed instructions on preparations of 4-page papers and poster presentations will be given on the Congress' website (under construction). The 4-page papers (not more and not less) will be published in the Proceedings. Authors will be encouraged to submit the full papers for publication in the Mechanics journals, in particular, in the Journal of Thermal Stresses.

## IMPORTANT DEADLINES

Submission of an abstract: November 30, 2012  
Notification of acceptance: January 15, 2013  
Submission of the 4-page paper: February 28, 2013

## CHAIRS

### General Chair

Prof. Cun-Fa Gao  
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### Co-Chairs

Prof. Richard B Hetnarski  
Rochester Institute of Technology, USA  
  
Prof. Naotake Noda  
Shizuoka University, Japan



## SOCIAL PROGRAMS

Rich program is scheduled, including sightseeing, etc.

## PREVIOUS CONGRESSES ON THERMAL STRESSES

9<sup>th</sup> Budapest, Hungary 2011

Budapest University of Technology and Economics  
and Hungarian Academy of Sciences

8<sup>th</sup> Urbana-Champaign, Illinois, USA 2009  
UIUC

7<sup>th</sup> Taipei, Taiwan 2007  
NTUST

6<sup>th</sup> Vienna, Austria 2005  
Vienna University of Technology

5<sup>th</sup> Blacksburg, USA 2003  
Virginia Polytechnic Institute and State University

4<sup>th</sup> Osaka, Japan 2001

Osaka Prefecture University, Osaka Institute of  
Technology

3<sup>rd</sup> Cracow, Poland 1999  
Cracow University of Technology

2<sup>nd</sup> Rochester, USA 1997  
Rochester Institute of Technology

1<sup>st</sup> Hamamatsu, Japan 1995  
Shizuoka University

## CORRESPONDENCE

Secretariat of TS 2013

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Website: <http://ts2013.nuaa.edu.cn> (under construction)



IUAM



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Nanjing University of Aeronautics and Astronautics

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Congress  
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Thermal  
Stresses